



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



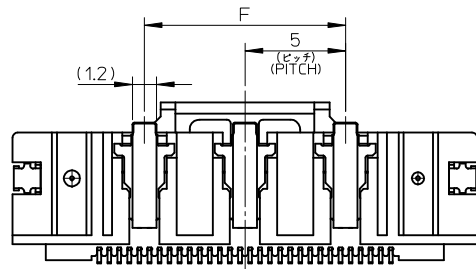
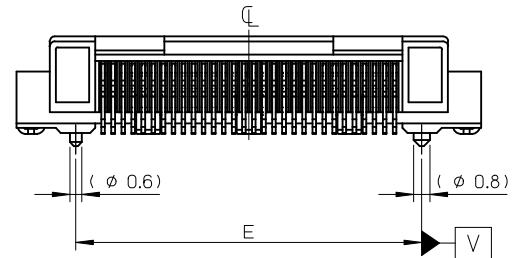
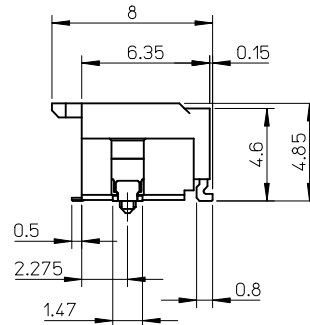
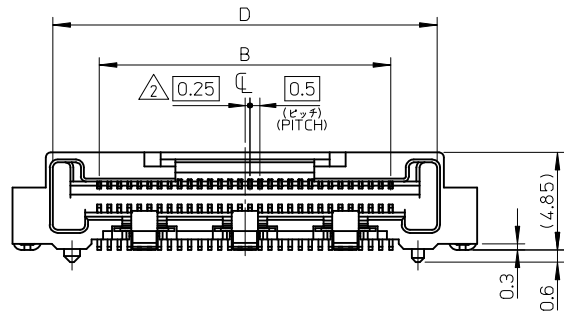
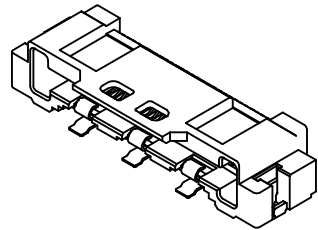
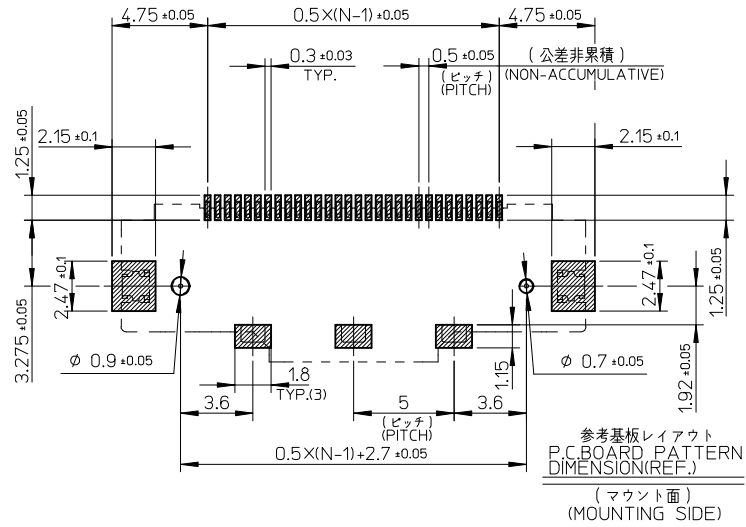
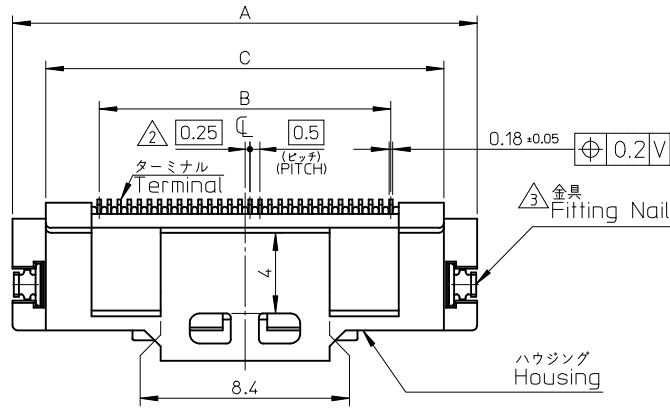
## Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

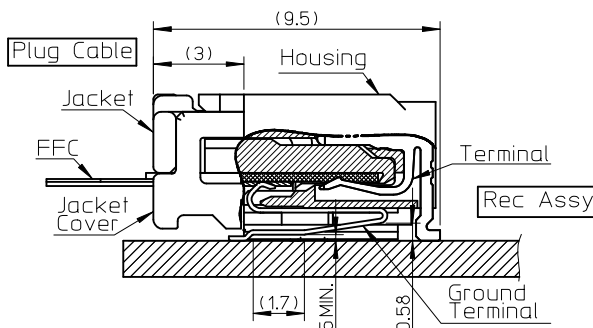
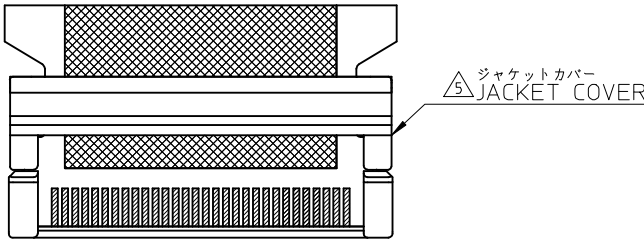
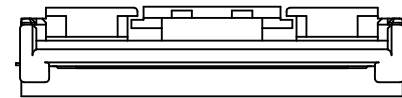
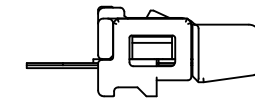
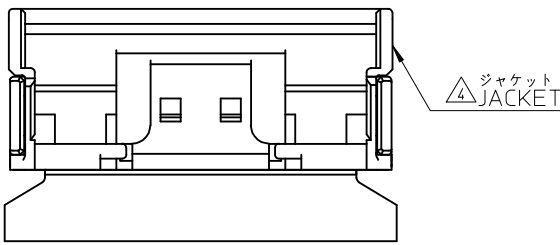




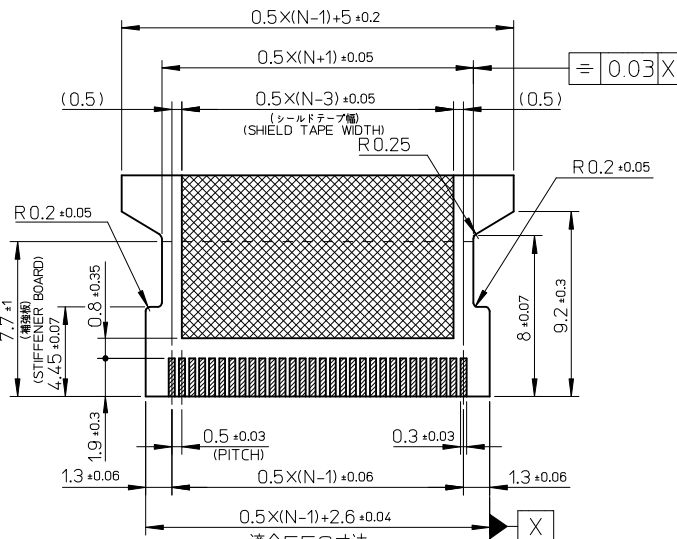
3	10	17.2	19.1	19.8	14.5	23.1	501864-3091	30
							EMBOSSED TAPE PKG.	極数
							ORDER No. オーダー番号	CIRCUIT

CONNECTOR SERIES No. 501864-xx31

REVISED EC NO: J2010-0779 DRWN: NISHI 2009/10/19 CHKD: MATSUURA 2009/10/19 APPR: MORIKAWA 2009/10/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	DOCUMENT NO. SD-501864-008			
REV	DESCRIPTION	ANGULAR ±1 °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3				



嵌合断面図  
MATED CONNECTOR SECTION



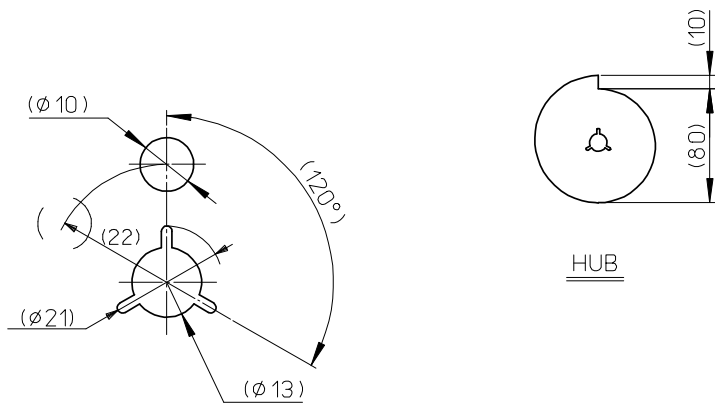
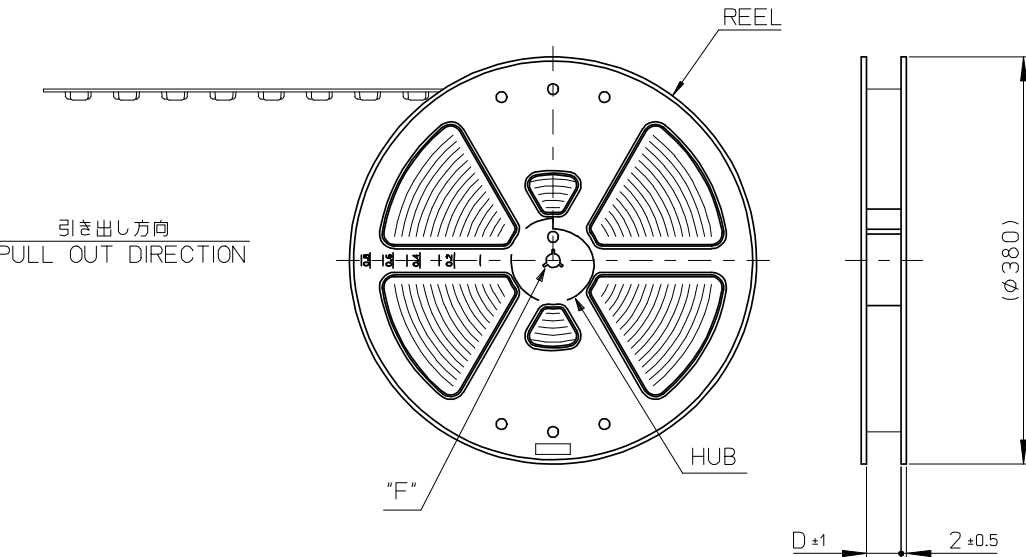
コネクタ接点部 CONTACT AREA  
シールド部 SHIELD AREA

適合FFC寸法 RECOMMENDED DIMENSION  
APPLICABLE FFC  
(仕上がり厚さ:コネクタ接点部 $0.3 \pm 0.03$ )  
:シールド部 $0.44 \pm 0.05$ )  
(THICKNESS:CONTACT AREA  $0.3 \pm 0.03$ )  
SHIELD AREA  $0.44 \pm 0.05$ )

注記  
NOTE

1. 使用材料 MATERIAL  
ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL94V-0 色:黒色  
LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED,UL94V-0 COLOR:BLACK  
ターミナル TERMINAL : 焼青銅 (t=0.18)  
PHOSPHOR BRONZE (t=0.18)  
メッキ仕様 PLATING  
接点部:金メッキ 0.1マイクロメートル以上  
CONTACT AREA:GOLD 0.1 MICROMETER MINIMUM  
半田付け部:金メッキ 0.05マイクロメートル以上  
SOLDER TAIL AREA:GOLD 0.05 MICROMETER MINIMUM  
下地メッキ:ニッケルメッキ 1.0マイクロメートル以上  
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM  
金具 FITTING NAIL : 焼青銅 (t=0.25)  
PHOSPHOR BRONZE (t=0.25)  
錫メッキ 1.0マイクロメートル以上  
TIN 1.0MICROMETER MINIMUM  
下地メッキ:ニッケルメッキ 1.0マイクロメートル以上  
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM  
グラウンド端子 GROUND TERMINAL : 焼青銅 (t=0.15)  
PHOSPHOR BRONZE (t=0.15)  
錫メッキ 1.0マイクロメートル以上  
TIN 1.0MICROMETER MINIMUM  
下地メッキ:ニッケルメッキ 1.0マイクロメートル以上  
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM
- △ N=偶数に適用 (N:極数)  
APPLY FOR N-EVEN IN CIRCUIT
- △ パターン剥離止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
- △ 適合ジャケット:501783-\*\*09  
製品詳細寸法はSD-501783-004を参照下さい。  
APPLICABLE JACKET:501783-\*\*09.  
RE DETAILED DIMENSION,SEE SD-501783-004.
- △ 適合ジャケットカバー:501784-\*\*08  
製品詳細寸法はSD-501784-005を参照下さい。  
APPLICABLE JACKET:501784-\*\*08.  
RE DETAILED DIMENSION,SEE SD-501784-005.
6. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

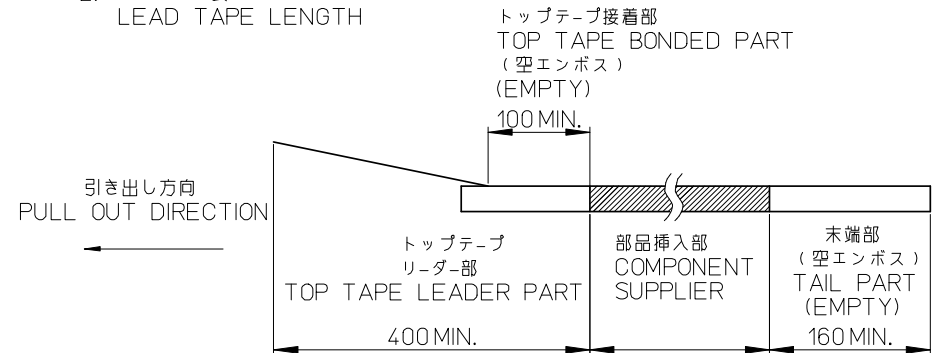
REVISED EC NO: J2010-0779 DRWN:NIISHI 2009/10/19 CHKD:MATSUURA 2009/10/19 APPR:KIMORI KAWA 2009/10/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)		
	10 OVER 30 UNDER	± 0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25			
	30 OVER	± 0.3	APPROVED BY H. HIRATA	DATE 07/12/25			
ANGULAR ±1 °		MATERIAL NO. SEE SHEET 1					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		DOCUMENT NO. SD-501864-008			SHEET NO. 2 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



DETAIL "F"

NOTES

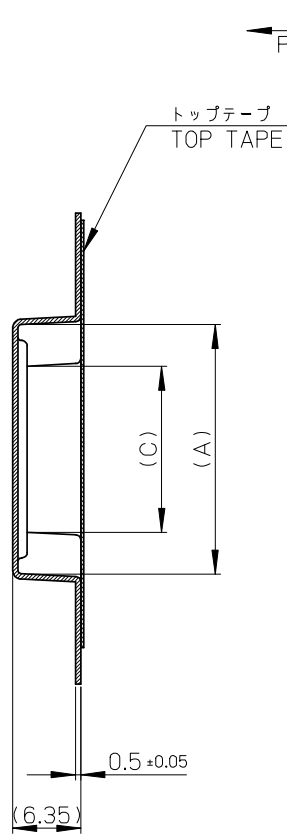
1. 梱包数量：900 個/リール  
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ  
LEAD TAPE LENGTH



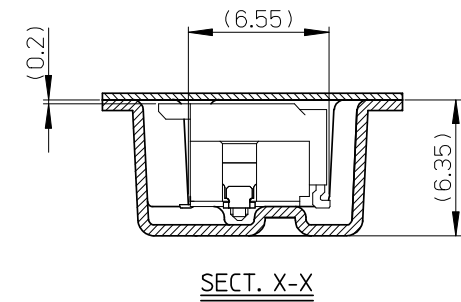
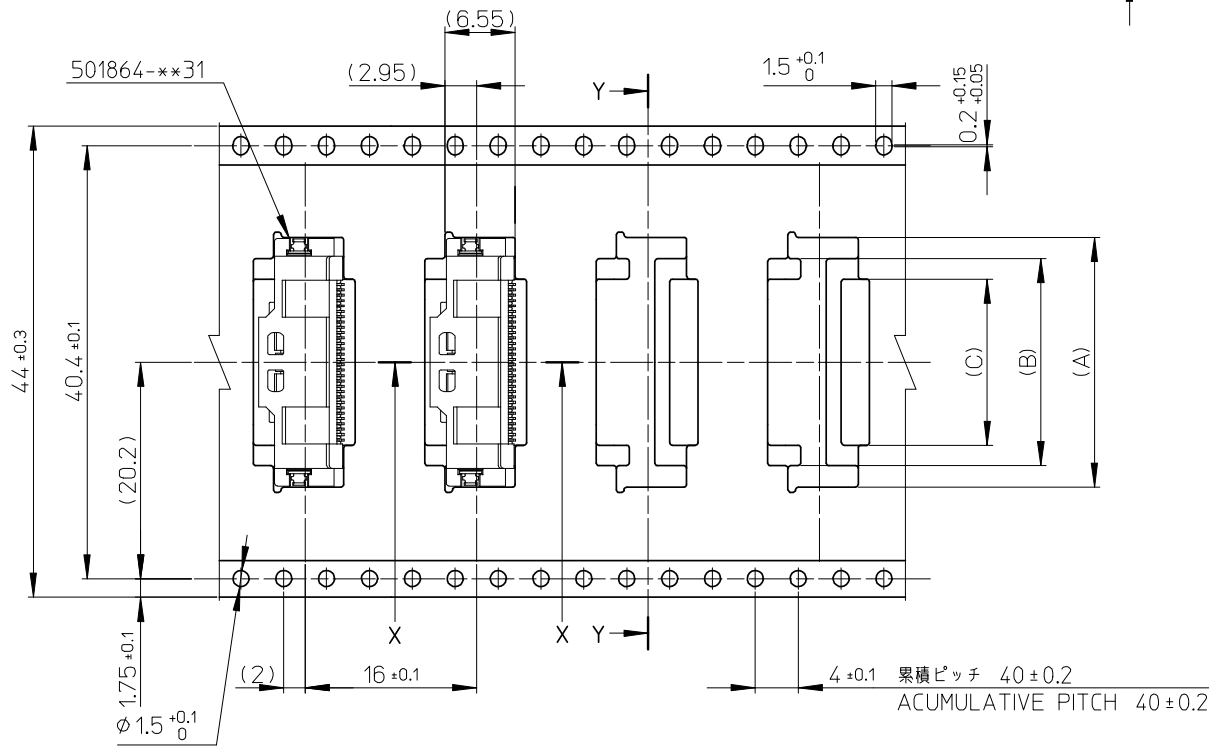
3. 製品詳細寸法については図面 SD-501864-008を参照下さい。  
RE DETAILED DIMENSION, SEE SD-501864-008.
4. 材料(MATERIAL)  
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)  
トップテープ(TOP TAPE)：PET, PE, PE  
リール(REEL)：ポリスチレン(POLYSTYRENE)
5. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

501864-\*\*91 MODEL NO.

RELEASED EC NO: J2008-2552 DRW:KSETO 2007/12/25 CHK:KMORIKAWA 2007/12/25 APPR:KMORIKAWA 2007/12/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25				
	30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	MOLEX INCORPORATED			
	ANGULAR	±1	MATERIAL NO. 501864-**91					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



引き出し方向  
PULL OUT DIRECTION



44	45.4	15.6	19.3	23.3	501864-3091	30
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CKT

SEE SHEET 1 OF 2 EC NO: J2008-2552 DRWN:KSETO 2007/12/25 CH'KD:KORIKAWA 2007/12/25 APPR:KORIKAWA 2007/12/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25			
	30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	MOLEX INCORPORATED		
	ANGULAR	±1	MATERIAL NO. 501864-***91	DOCUMENT NO. SD-501864-009			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				